

Korean International Semiconductor Conference & Exhibition on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

Session Date November 12 (Wed.), 2025

Session Time 14:10-15:50

Session Room F (Panorama Room, 16F)

[WeF2-1] [Invited] 14:10-14:30

Development of an Eco-Friendly Photoresist Stripper for Advanced Semiconductor Packaging Processes

Bo Yeon Lee, Sangseung Park, Seungeun Lee, Ga Young Kim, Seok Jin Hong, and Jung Shik Heo (ENF Technology Co., Ltd., Korea)

[WeF2-2] [Invited] 14:30-14:50

FINE Cut and FINE Forming (TGV) of HBM4, Glass Core and Interposer

Seak-Joon Lee (ITI, Korea)

[WeF2-3] [Invited] 14:50-15:10

Glass Package Substrates for High-Performance Chiplet Systems

Jimin Kwon (UNIST, Korea)

[WeF2-4] [Invited] 15:10-15:30

Bonding Strength and Fracture Behavior in Patterned Cu-SiO₂ Hybrid Interfaces

Ah-Young Park (Univ. of Seoul, Korea), Hakyung Jeong (KIMM, Korea), and Kyung-Ho Park (KANC, Korea)

[WeF2-5] [Invited] 15:30-15:50

Development of Optical Interconnection Core Technologies for Implementation and Reliability Enhancement of Co-Packaged Optics

Hongyun So, Keuntae Baek, and Animesh Sinha (Hanyang Univ., Korea)